

IN THE CLAIMS:

Cancel claims 2 through 4.

Please amend the claims as follows:

1. (Currently Amended) A method for making a transistor comprising:  
providing a substrate;  
forming a dielectric layer on a portion of the substrate;  
forming a gate structure on the dielectric layer having a transition layer formed on the dielectric layer and a metal silicide layer formed on the transition layer, the gate structure having a first sidewall and a second sidewall, the first sidewall and the second sidewall defining therebetween within the substrate a first contact region, a channel region and a second contact region; and  
forming first, second, and third subregions within the second contact region, each subregion having a dopant concentration that differs from that of the other two subregions, forming of the first, second, and third subregions comprising:  
depositing a conformal layer of dielectric material having a first thickness over the substrate;  
anisotropically etching the conformal layer of dielectric material[[,]] forming a layer of dielectric material on the first sidewall and the second sidewall;  
subjecting the layer of dielectric material on the first sidewall and the second sidewall to an annealing/oxidation process;  
forming a single layer sidewall spacer having a second thickness greater than the first thickness of the dielectric material overlying the first sidewall and the second sidewall;  
introducing a first dopant into the substrate to form the first subregion;  
forming another single layer sidewall spacer overlying the single layer sidewall spacer, the another single layer sidewall spacer having a third thickness intermediate the

first thickness of the dielectric layer and the second thickness of the single layer  
sidewall spacer;

introducing a second dopant into the substrate to form the second subregion;

substantially removing the another single layer sidewall spacer; and

introducing a third dopant into the substrate to form the third subregion.

2. (Canceled)

3. (Canceled)

4. (Canceled)

5. (Previously Presented) The method of claim 1, wherein the another single layer  
sidewall spacer comprises a material of one of silicon nitride and silicon dioxide.